



2010 IEEE International Conference on Vehicular Electronics and Safety

Sponsored by the IEEE Intelligent Transportation Systems Society Qingdao, China, July 15-17, 2010 <u>http://www.ieeeves.org</u>

VENUE

ICVES'10 will be held jointly with 2010 IEEE/ASME International Conference on Mechatronic and Embedded Systems and Applications and 2010 IEEE International Conference on Service Operations and Logistics, and Informatics.

The International Conference on Vehicular Electronics and Safety (ICVES'10) is an annual forum sponsored by the IEEE Intelligent Transportation Systems (ITS) Society. It brings together researchers and practitioners to discuss vehicle electronics, and safety systems research and practice. ICVES'10 welcomes papers dealing with any aspect of vehicle electronics and safety systems.

TOPICS OF INTEREST

- Active and Passive Safety Systems
- Telematics
- Vehicular Power Networks
- X-By Wire Technology
- System-on-a-Chip
- Vehicular Sensor
- Vehicle Bus
- Sensor Network
- Embedded Operation System
- Electro Magnetic Compatibility
- Inter-Vehicular Network
- Vehicle Testing
- Vehicle Hardware /Software System

CONFERENCE ORGANIZING COMMITTEE

General Chair

Yaobin Chen, Purdue University-Indianapolis, USA General Co-Chair Petros Ioannou, Uni of Southern California, USA Program Co-Chairs Lingxi Li Purdue University-Indianapolis, USA Glenn Widmann Delphi Electronics and Safety, USA

PAPER SUBMISSION

- Navigation and Localization Systems
- Vehicular Measurement Technology
- Vehicular Signal Processing
- Micro-electromechanical Systems
- Image Sensor
- Vehicle/Engine Control
- Driver Assistance Driving Systems
- Adaptive Cruise Control Systems
- Pattern Recognition for Vehicles
- Human Machine Interaction
- Diagnostics on Line
- Virtual/Digital System

Publicity Chair Gongyou Tang, Ocean University of China, China Finance Chair Yanqing Gao, University of Arizona, USA Publication Chair Guanpi Lai, University of Arizona, USA Local Organizing Chair Nan Zhang, Chinese Academy of Sciences, China

Complete manuscripts in PDF must be electronically submitted at the conference website: <u>http://www.ieeeves.org</u> Manuscripts should be at most six (6) pages in the IEEE two-column format including figures, tables, and references. Please refer to the conference website for the most up-to-date information <u>http://www.ieeeves.org</u>. Contact us at: <u>ieeeves2010@gmail.com</u>

IMPORTANT DATES

March 7, 2010 Paper submission deadline

May 4, 2010 Notification of acceptance

May 25, 2010 Camera-ready copy due